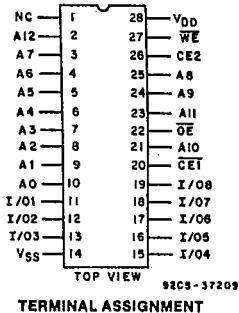


CDM6264



CMOS 8192-Word by 8-Bit LSI Static RAM

Features:

- Fully static operation
- Single power supply: 4.5 V to 5.5 V
- All inputs and outputs directly TTL compatible
- Industry standard 28-pin configuration
- Input address buffers gated off with chip disable
- 3-state outputs

The RCA-CDM6264 is a 8192-word by 8-bit static random-access memory. It is designed for use in memory systems where high-speed, low power and simplicity in use are desirable. This device has common data input and data output and utilizes a single power supply of 4.5 V to 5.5 V.

Either chip enable ($\overline{CE1}$ or $\overline{CE2}$), when not valid, will gate off the address and output buffers and power down the chip to

minimum standby power with inputs toggling. The output enable (\overline{OE}) controls the output buffers to eliminate bus contention.

The CDM6264 is supplied in a 28-lead dual-in-line plastic (E suffix) package.

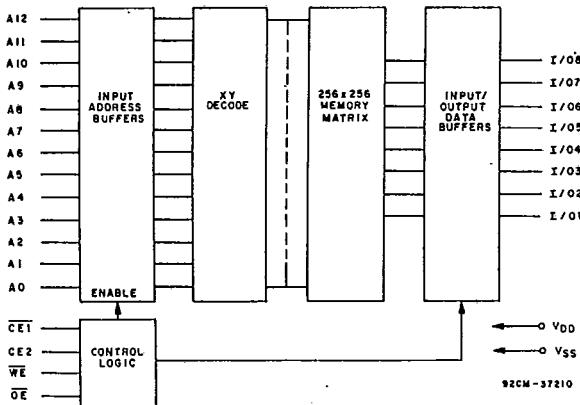


Fig. 1 - Functional block diagram.

	CDM6264-3	CDM6264-2I
Access Time (max.)	150 ns	200 ns
Output Enable Time (max.)	70 ns	70 ns
Operating Current (max.)	45 mA	45 mA
Standby Current I_{DDB1} (max.)	100 μ A	200 μ A
Operating Temp. Range:	0°C to +70°C	-40°C to +85°C
Data Retention Voltage:		
0°C $\leq T_A \leq$ +70°C	2 V min.	—
0°C $\leq T_A \leq$ +85°C	—	2 V min.
-40°C $\leq T_A <$ 0°C	—	4 V min.

TRUTH TABLE

$\overline{CE1}$	$\overline{CE2}$	\overline{OE}	\overline{WE}	A0 TO A12	MODE	DATA I/O	DEVICE CURRENT
H	X	X	X	X	NOT SELECTED	HIGH Z	STANDBY
X	L	X	X	X	NOT SELECTED	HIGH Z	STANDBY
L	H	L	H	STABLE	READ	DATA OUT	ACTIVE
L	H	X	L	STABLE	WRITE	DATA IN	ACTIVE
L	H	H	H	STABLE	OUTPUT DISABLE	HIGH Z	ACTIVE

L = LOW H = HIGH X = H OR L

MAXIMUM RATINGS, Absolute-Maximum Values:

DC SUPPLY-VOLTAGE RANGE, (V_{DD}): (Voltage referenced to V_{SS} terminal)	-0.3 to +7 V
INPUT VOLTAGE RANGE, ALL INPUTS	-0.3 to +7 V
POWER DISSIPATION PER PACKAGE (P_D): For $T_A = -40^\circ$ to $+60^\circ$ C	500 mW
For $T_A = +60^\circ$ to $+85^\circ$ C	Derate linearly at 8 mW/ $^\circ$ C to 300 mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR For $T_A =$ FULL PACKAGE-TEMPERATURE RANGE	100 mW
OPERATING-TEMPERATURE RANGE (T_A): CDM6264-3	0° to $+70^\circ$ C
CDM6264-2I	-40° to $+85^\circ$ C
STORAGE TEMPERATURE RANGE (T_{stg})	-55 to $+125^\circ$ C
LEAD TEMPERATURE (DURING SOLDERING): At distance $1/16 \pm 1/32$ in. (1.59 ± 0.79 mm) from case for 10 s max.	$+265^\circ$ C

OPERATING CONDITIONS at $T_A = 0^\circ$ to $+70^\circ$ C (CDM6264-3); $T_A = -40^\circ$ to $+85^\circ$ C (CDM6264-2I)

For maximum reliability, operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	LIMITS		UNITS
	ALL TYPES		
	MIN.	MAX.	
DC Operating Voltage Range	4.5	5.5	V
Input Voltage Range	V_{IH}	$V_{DD} + 0.3$	
	V_{IL}	0.8	
Input Signal Rise or Fall Time Δ	t_r, t_f	5	μ s



Δ Input signal rise and fall times with a duration greater than the maximum value can cause loss of stored data in the selected mode.

STATIC ELECTRICAL CHARACTERISTICS at $T_A = 0^\circ$ to $+70^\circ$ C (CDM6264-3); $T_A = -40^\circ$ to $+85^\circ$ C (CDM6264-2I),

$V_{DD} = 5$ V \pm 10%, Except as noted

CHARACTERISTIC	CONDITIONS	LIMITS						UNITS	
		CDM6264-3			CDM6264-2I				
		Min.	Typ.*	Max.	Min.	Typ.*	Max.		
Standby Device Current	I_{DDs}	—	1.5	3	—	2	4	mA	
	I_{DDs1}	—	5	100	—	10	200	μ A	
Output Voltage Low Level	V_{OL} Max.	—	—	0.4	—	—	0.4	V	
		$I_{OL} = 1$ mA	—	0.1	—	0.1	—		
Output Voltage High Level	V_{OH} Min.	2.4	—	—	2.4	—	—	V	
		$I_{OH} = -1$ mA	—	$V_{DD} - 0.1$	—	$V_{DD} - 0.1$	—		
Input Leakage Current	I_{IN} Max.	—	± 0.1	± 2	—	± 0.1	± 2	μ A	
3-State Output Leakage Current	I_{OUT}	—	± 0.5	± 2	—	± 0.5	± 2	μ A	
Operating Device Current	$I_{OPER1}^{\#}$	—	4.5	9	—	7.5	15	mA	
		$V_{IN} = V_{IL}, V_{IH}$	—	22.5	45	—	22.5		45
		$t_{cyc} = 1$ μ s	—	2	4	—	5		10
	$I_{OPER2}^{\#}$	—	20	40	—	20	40	mA	
	$V_{IN} = 0.2$ V, $t_{cyc} = 1$ μ s	—	2	4	—	5	10		
	$V_{DD} = 0.2$ V, $t_{cyc} = \text{min. cycle time}$	—	20	40	—	20	40		
Input Capacitance	C_{IN}	—	4	6	—	4	6	pF	
Output Capacitance	C_{IO}	—	6	8	—	6	8		

*Typical values are for $T_A = 25^\circ$ C and nominal V_{DD} .

#Outputs open circuited.

CDM6264

SIGNAL DESCRIPTIONS

- A0-A12 (Address Inputs):** These inputs must be stable prior to a write operation, but may change asynchronously during read functions.
- I/O1-I/O8:** 8-bit tristate data bus.
- CE1, CE2 (Chip Enable):** Either chip enable, when not true, powers down the chip, disables Read and Write functions, and gates off address and output buffers.
- OE (Output Enable):** Enables tristate outputs if $\overline{CE1}$ and $CE2$ are valid and \overline{WE} is high.
- WE (Write Enable):** Enables Write function, if $\overline{CE1}$ and $CE2$ are valid. \overline{WE} will dominate if both \overline{WE} and \overline{OE} are low (i.e., the bus will be tristated and a Write will occur).
- V_{DD}, V_{SS}:** Power supply connections.

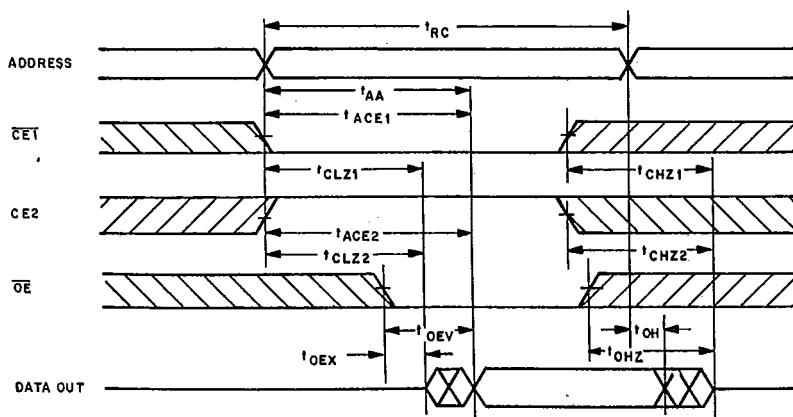
DYNAMIC ELECTRICAL CHARACTERISTICS at T_A = 0° to +70° C (CDM6264-3);

T_A = -40° to +85° C (CDM6264-2I), V_{DD} = 5 V ± 10%,

Input t_r, t_f = 10 ns; C_L = 100 pF and 1 TTL Load, Input Pulse Levels: 0.8 V to 2.4 V

CHARACTERISTIC		LIMITS				UNITS
		CDM6264-3		CDM6264-2I		
		MIN.†	MAX.	MIN.†	MAX.	
Read Cycle Times, See Fig. 2						
Read Cycle Time	t _{RC}	150	—	200	—	ns
Address Access Time	t _{AA}	—	150	—	200	
Chip Enable Access Time	t _{ACE1} , t _{ACE2}	—	150	—	200	
Chip Enable to Output Active	t _{CLZ1} , t _{CLZ2}	10	—	10	—	
Output Enable to Output Valid	t _{OEV}	—	70	—	70	
Output Enable to Output Active	t _{OEX}	5	—	5	—	
Chip Disable to Output "High Z"	t _{CHZ1} , t _{CHZ2}	0	70	0	70	
Output Disable to Output "High Z"	t _{OHZ}	0	60	0	60	
Output Hold from Address Change	t _{OH}	30	—	30	—	

† Time required by a limit device to allow for the indicated function.



\overline{WE} IS HIGH DURING READ CYCLE. TIMING MEASUREMENT REFERENCE LEVEL IS 1.5 V.

92CM-37205

Fig. 2 - Read-cycle timing waveforms.

DYNAMIC ELECTRICAL CHARACTERISTICS at $T_A = 0^\circ$ to $+70^\circ$ C (CDM6264-3);

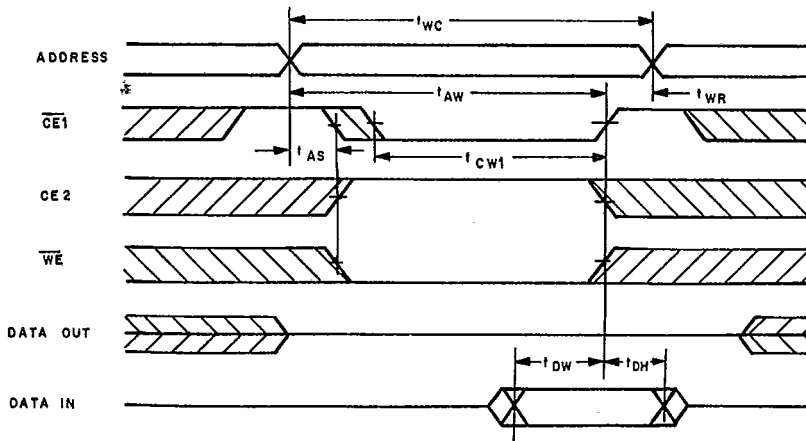
$T_A = -40^\circ$ to $+85^\circ$ C (CDM6264-2I), $V_{DD} = 5\text{ V} \pm 10\%$,

Input $t_r, t_f = 10\text{ ns}$; $C_L = 100\text{ pF}$ and 1 TTL Load, Input Pulse Levels: 0.8 V to 2.4 V

CHARACTERISTIC		LIMITS				UNITS
		CDM6264-3		CDM6264-2I		
		MIN. [†]	MAX.	MIN. [†]	MAX.	
Write Cycle Times, See Fig. 3						
Write Cycle Time	t_{wc}	150	—	200	—	ns
Chip Enable to End of WRITE	t_{cw1}, t_{cw2}	120	—	170	—	
Address Valid to End of WRITE	t_{aw}	120	—	170	—	
Address Setup Time	t_{as}	0	—	0	—	
Write Enable Width	t_{ww}	100	—	120	—	
Write Recovery Time	t_{wr}	0	—	0	—	
Write to Output "High Z"	t_{whz}	—	70	—	80	
Input Data Setup Time	t_{dw}	60	—	80	—	
Input Data Hold Time	t_{dh}	0	—	0	—	
Output Active from End of Write	t_{ow}	10	—	10	—	

[†]Time required by a limit device to allow for the indicated function.

WRITE CYCLE 1 (CE1 CONTROL)

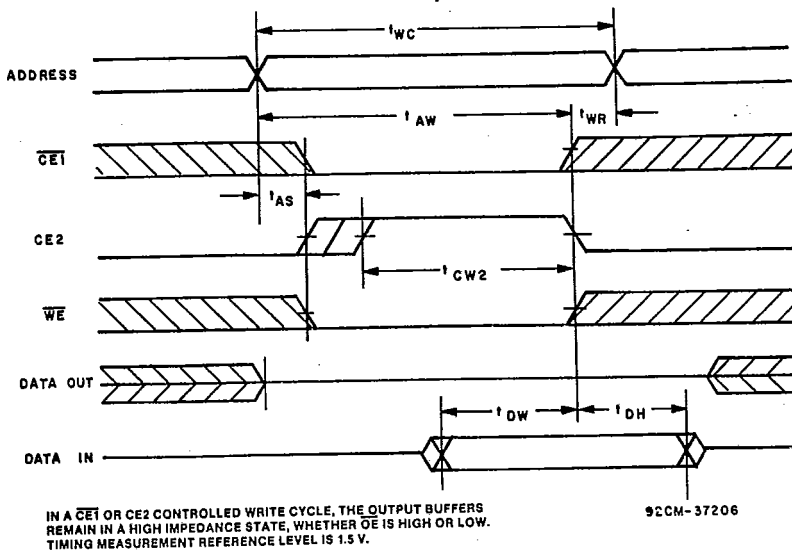


IN A CE1 OR CE2 CONTROLLED WRITE CYCLE, THE OUTPUT BUFFERS REMAIN IN A HIGH IMPEDANCE STATE, WHETHER OE IS HIGH OR LOW. TIMING MEASUREMENT REFERENCE LEVEL IS 1.5 V.

92CM-37204

Fig. 3 - Write-cycle timing waveforms.

WRITE CYCLE 2 (CE2 CONTROL)



WRITE CYCLE 3 (\overline{WE} CONTROL)

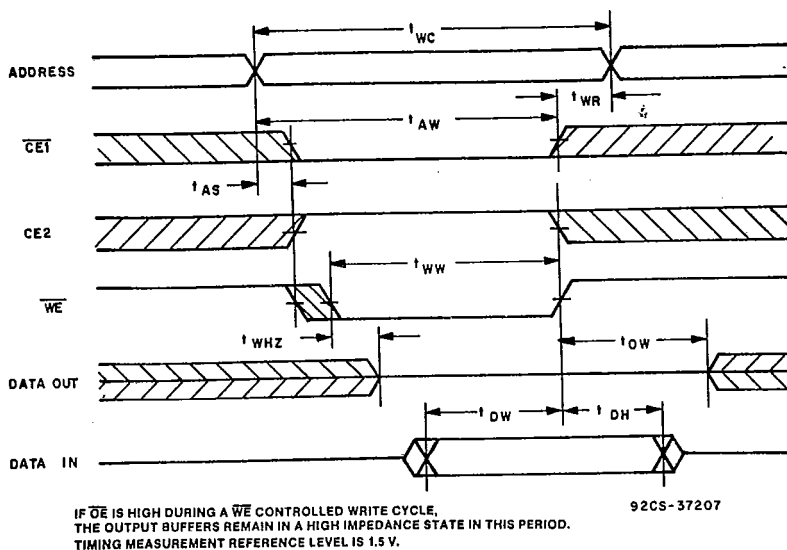


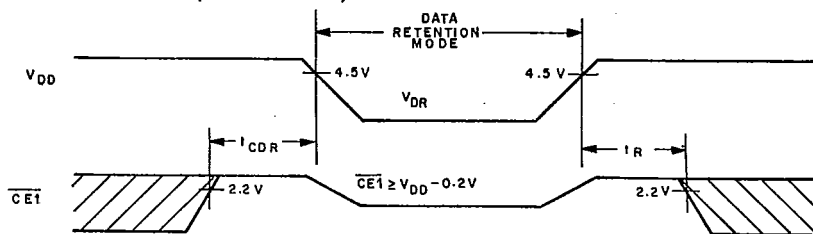
Fig. 3 - Write-cycle timing waveforms (cont'd).

DATA RETENTION CHARACTERISTICS, See Fig. 4.

CHARACTERISTIC	TEST CONDITIONS	LIMITS				UNITS
		CDM6264-3		CDM6264-2I		
		Min.	Max.	Min.	Max.	
Minimum Data Retention Voltage V_{DR}	$CE1 \geq V_{DD} - 0.2 V$, or $CE2 \leq 0.2 V$; $0^{\circ}C \leq T_A \leq +70^{\circ}C$ $0^{\circ}C \leq T_A \leq +85^{\circ}C$ $-40^{\circ}C \leq T_A < 0^{\circ}C$	2	—	—	—	V
Data Retention Quiescent Current I_{DDDR}	$CE1, CE2 \geq V_{DD} - 0.2 V$, or $CE2 \leq 0.2 V$; $V_{DD} = 3 V, 0^{\circ}C \leq T_A \leq +70^{\circ}C$ $V_{DD} = 3 V, 0^{\circ}C \leq T_A \leq +85^{\circ}C$ $V_{DD} = 4 V, -40^{\circ}C \leq T_A < 0^{\circ}C$	—	50	—	—	μA
Chip Disable to Data Retention Time t_{CDR}	See Fig. 4	0	—	0	—	ns
Recovery to Normal Operation Time t_R	See Fig. 4	* t_{RC}	—	* t_{RC}	—	

* t_{RC} = Read Cycle Time.

DATA RETENTION WAVEFORM 1 ($\overline{CE1}$ CONTROL)



DATA RETENTION WAVEFORM 2 ($CE2$ CONTROL)

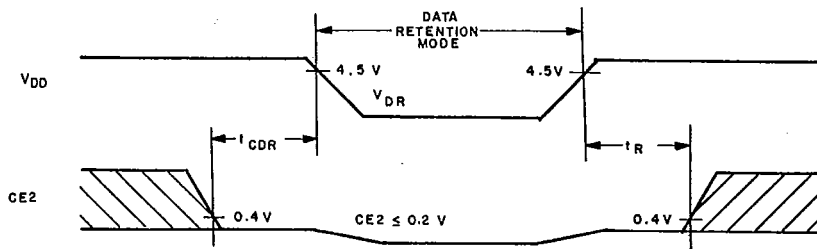


Fig. 4 - Low V_{DD} data-retention timing waveforms. 92CM -37208